

Supplementary Information

Room-Temperature Electrochemical Co-deposition of Cu-MOF/CNT Heterostructures on Carbon Fibers for Efficient Microwave Absorption at Low Filler Loading

Yuting Guo^{a,†}, Qinyang Xiong^{a,†}, Xiaojie Yang^a, Ke Han^a, Jiahao Gao^a, Danlin Yan^b, Xuejun Zhang^{a,*}, Jiangman Sun^{a,*}, Yanhong Tian^{a*}

^a Key Laboratory of Carbon Fiber and Functional Polymers, Ministry of Education, State Key Laboratory of Organic-Inorganic Composites, College of Materials Science and Engineering, Beijing University of Chemical Technology, Beijing, 100029, China

^b School of Science, Guangdong University of Petrochemical Technology, Maoming, Guangdong, 525000, China

† These authors contribute equally

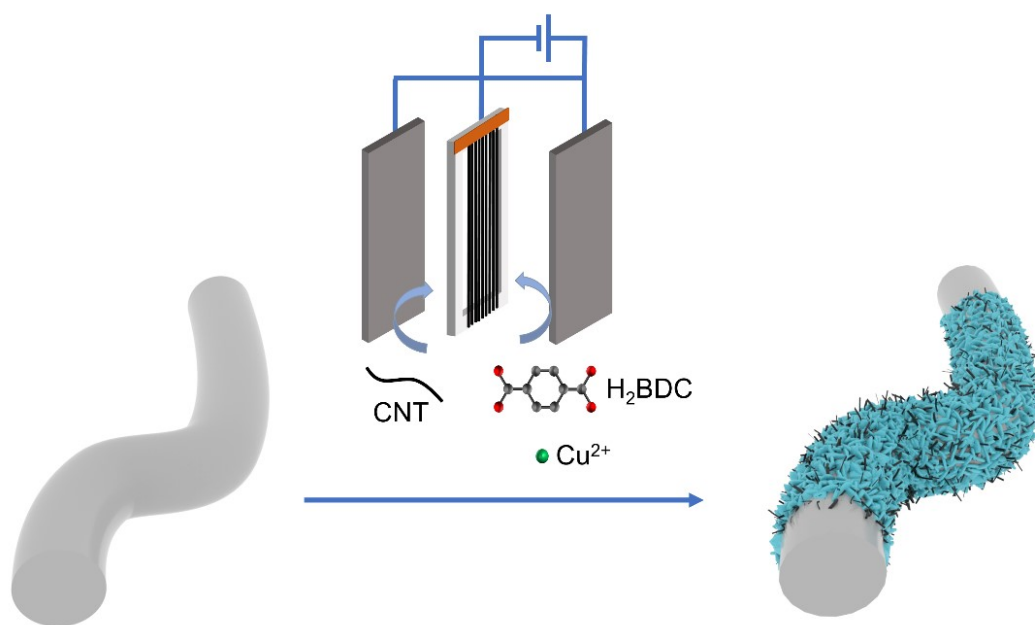


Figure S1. Schematic illustration of the preparation process of Cu-MOF/CNT@CF

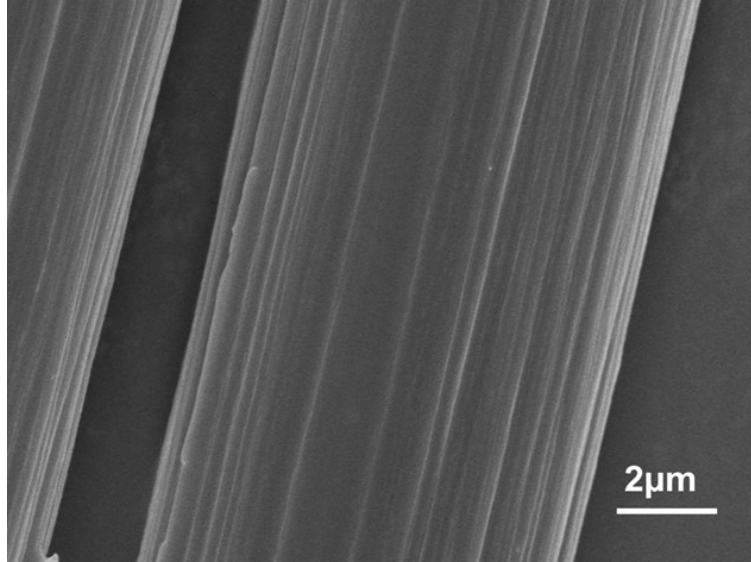


Figure S2. SEM images of SA@CF

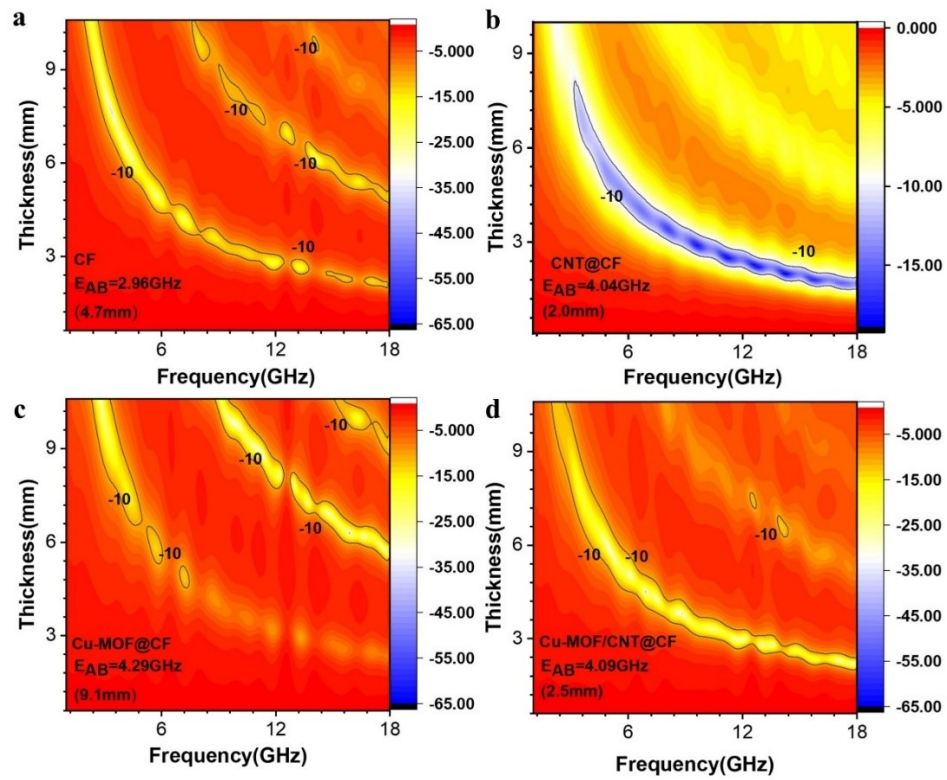


Figure S3. 2D diagrams of reflection loss for the as-prepared samples: (a) CF, (b) CNT@CF, (c) Cu-MOF@CF, (d) Cu-MOF/CNT@CF

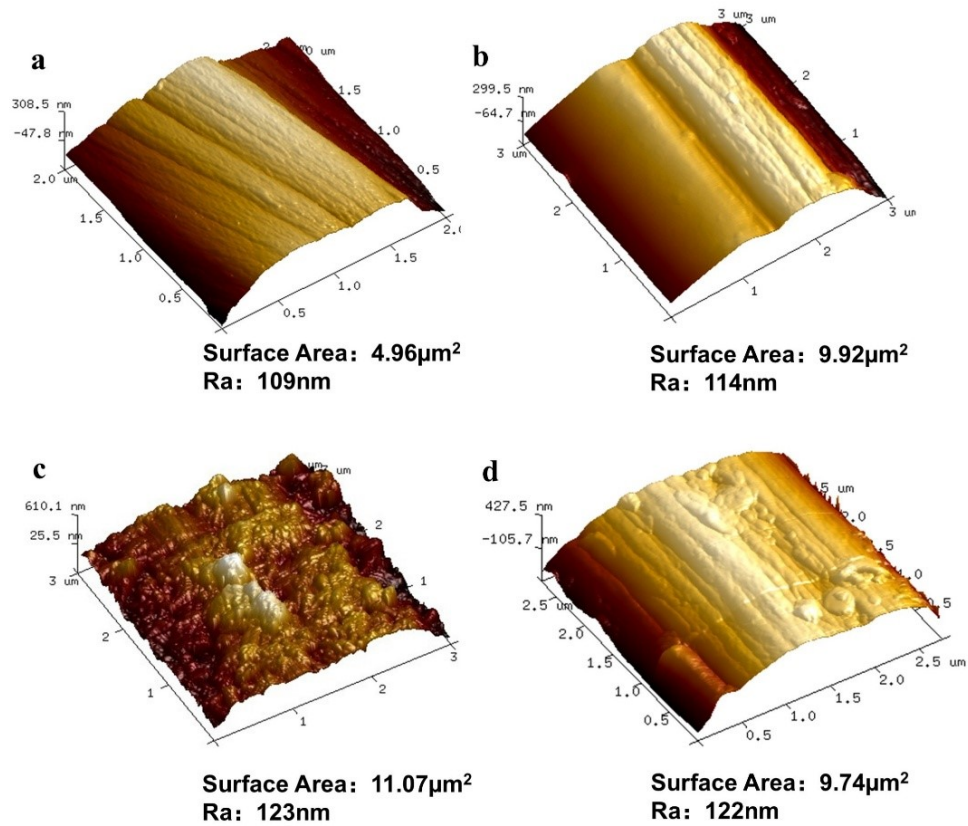


Figure S4. AFM images of (a) CF, (b) CNT@CF, (c) Cu-MOF@CF, (d) Cu-MOF/CNT@CF

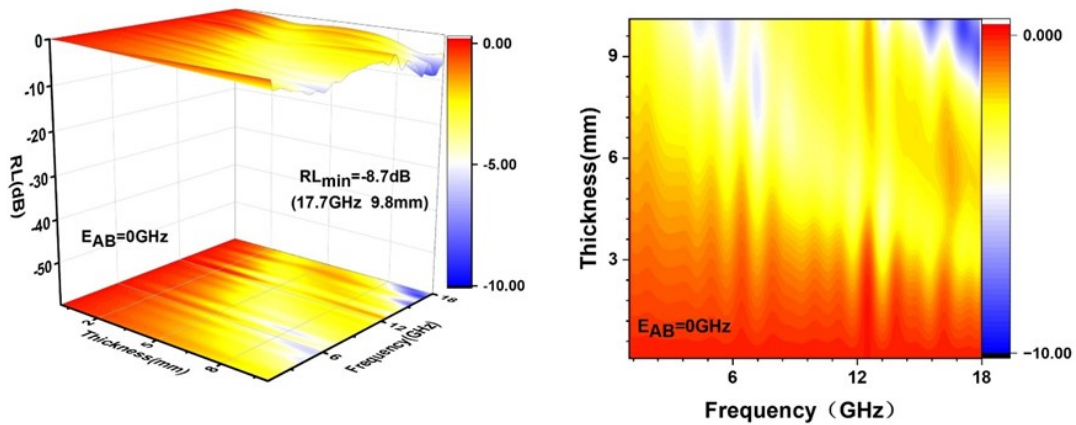


Figure S5. 3D diagrams and 2D diagrams of reflection loss for Cu-MOF

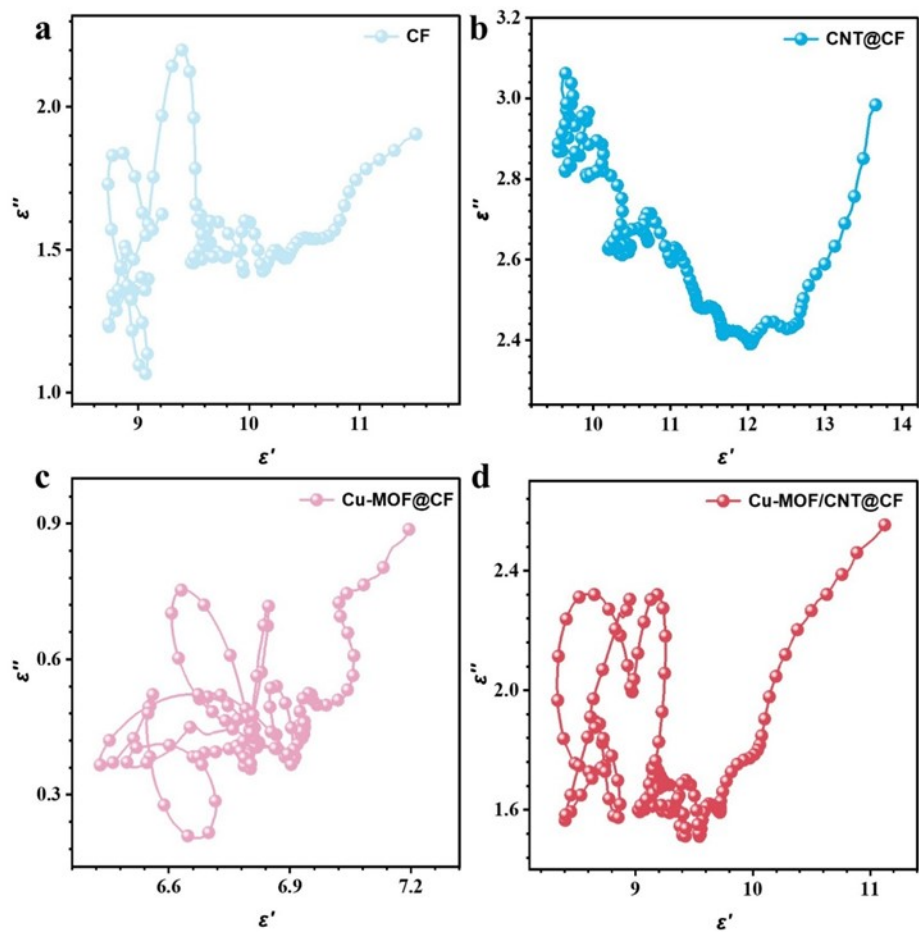


Figure S6. Cole-Cole curves of (a) CF, (b) CNT@CF, (c) Cu-MOF@CF, (d) Cu-MOF/CNT@CF